## Product / Package Information

| | |
|---|---|
| **Package** | WLCSP |
| **Body Size** | |
| **I/O Count** | 9 |
| **Terminal Finish** | SnAgCu |
| **MS Number** | MS011112A |

## Environmental Information

| | |
|---|---|
| **RoHS Compliant** | Yes |
| **High Temperature Compliant** | Yes |
| **Halogen Free Compliant** | Yes |
| **REACH SVHC Compliant** | Yes |

# Materials Declaration

### Chip

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Doped Silicon | 7440-21-3 | 1.67 E-03 | 100.00 | 1000000 | 62.55 | 625510 |

### Wafer Bumps

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Tin & its alloys | Tin | 7440-31-5 | 9.09E-04 | 96.80 | 968000 | 34.00 | 340038 |
| Tin & its alloys | Silver | 7440-22-4 | 2.44E-05 | 2.60 | 26000 | 0.91 | 9133 |
| Tin & its alloys | Copper | 7440-50-8 | 5.64E-06 | 0.60 | 6000 | 0.211 | 2108 |
| Subtotal | | | 9.39E-04 | 100.00 | 1000000 | 35.13 | 351279 |

### UBM / RDL

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Copper & its alloys | Copper | 7440-50-8 | 1.79 E-05 | 65.23 | 652287 | 0.67 | 6687 |
| Precious metals | Nickel | 7440-02-0 | 7.01 E-06 | 25.59 | 255892 | 0.262 | 2623 |
| Other non-ferrous metals and alloys | Titanium | 7440-32-6 | 2.30 E-06 | 8.39 | 83907 | 0.086 | 860 |
| Other non-ferrous metals and alloys | Vanadium | 7440-62-2 | 2.17 E-07 | 0.79 | 7914 | 0.008 | 81 |
| Subtotal | | | 2.74 E-05 | 100.00 | 1000000 | 1.03 | 10252 |

### Polyimide

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other organic materials | Resin | Proprietary | 2.35 E-05 | 67.95 | 679500 | 0.88 | 8806 |
| Other organic materials | Tetraethylene Glycol Dimethacrylate | 109-17-1 | 5.05 E-06 | 14.56 | 145600 | 0.189 | 1887 |
| Other organic materials | Trifluoroacetic Anhydride | 407-25-0 | 2.02 E-06 | 5.83 | 58300 | 0.076 | 756 |
| Other organic materials | 4,4'-Oxydiphthalic Anhydride | 1823-59-2 | 2.02 E-06 | 5.83 | 58300 | 0.076 | 756 |
| Other organic materials | 2-Hydroxyethyl Methacrylate | 868-77-9 | 2.02 E-06 | 5.83 | 58300 | 0.076 | 756 |
| Subtotal | | | 3.47 E-05 | 100.0 | 1000000 | 1.30 | 12960 |

| | | | **Weight (g)** | | | **Percentage (%)** | **PPM** |
|---|---|---|---|---|---|---|---|
| **Package Totals** | | | **2.67 E-03** | | | **100** | **1000000** |

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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